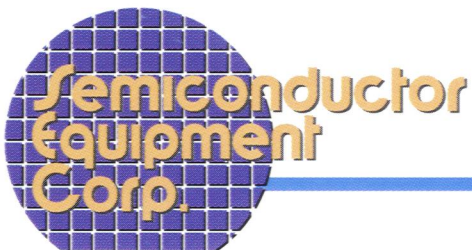


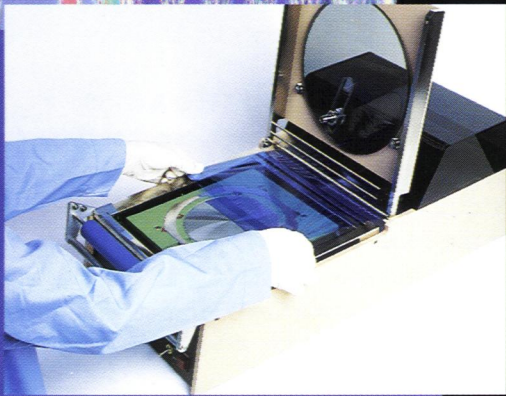
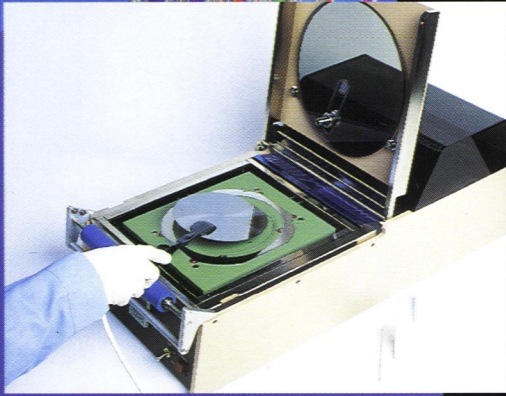


MODEL 3100 3150 Wafer/Frame Tape Applicators

Semiconductor Equipment Corporation's Model 3100 & 3150 Wafer/Film Frame Tape Applicators apply tape with optimal control of temperature and pressure parameters. Uniform, bubble-free mounting of tape for wafer dicing is the result. State-of-the-art features make them two of the most advanced systems available. The Model 3100 handles wafers up to 6" in diameter, while the Model 3150 handles any size wafer up to 8" in diameter. Both models are so versatile, they can operate with virtually any film frame.

- Bubble-Free Tape Application
- Safe, Accurate Tape Trimming System
- Uniform Tape Tensioner
- Works with All Standard Film Frames
- Adjustable, Machine Controlled Roller Pressure
- Closed Loop Temperature Control
- Optional Non-Contact Platen
- Optional Static Eliminator





Bubble Free Tape Application

The captive roller applies the tape to the wafer and film frame in a manner that excludes entrapped air. The result is bubble-free tape mounting.

Safe, Accurate Tape Trimming System

The tape cutting system is fast, safe and accurate. It includes cutting blades which automatically retract when not in use, thereby preventing injury.

Uniform Tape Tensioner

The tape is held by the tensioning frame until it is rolled into contact with the wafer and film frame. Tape is stretched uniformly in all directions.

Works with All Standard Film Frames

Frames are accurately positioned against locating pins and magnets hold the frames in place.

Adjustable, Machine Controlled Roller Pressure

The captive roller and spring loaded platen work together to guarantee repeatable mounting pressure. Repeatable pressure is important for repeatable adhesion. Spring tension may be set at various levels.

Closed Loop Temperature Control

A digital temperature controller regulates platen temperature up to 75°C. Repeatable mounting temperature is important for repeatable adhesion.

Optional Non-Contact Platen

When it is undesirable for the face of the wafer to come into contact with the platen, an optional Non-Contact Platen is available. With the non-contact platen, the wafer is held in position by vacuum along a narrow ridge around the perimeter. A pressure backup supports the wafer during the tape application. The majority of the wafer remains untouched.

Optional Static Eliminator

Located in the tape path, this device prevents static electricity from building up in the tape.

Specifications

MODEL 3100		MODEL 3150	
Weight	75 lbs.	Weight	90 lbs.
Height	8"	Height	8"
Length	28"	Length	32"
Width	14"	Width	17"
Shipping Wt:	80 lbs.	Shipping Wt:	100 lbs.
Voltage: 110 or 220 VAC - 50/60 Hz • Vacuum: 25" H ₂ O • Current: 3Amps			



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